

## Vacuum Batch Reflow Vapour Phase Soldering Oven



The VAC-Series is an environmentally friendly and flexible soldering system dedicated for highest quality soldering. The patented vacuum chamber located in the process chamber ensures that highest solder quality with a minimum amount and size of voids is possible. Outstanding performance and quality results through the unique technology applied in these machines. Regardless of the number of layers in the board and high mix of components this machine can handle the toughest applications with fantastic results. The Intelligent Profiling System gives the user full control of temperature rise to reach the best and desired soldering profiles. Together with the unique patented Soft Vapour Phase there is no fear of exceeding temperature increase rates of components. Their outstanding low energy consumption and exhaust air volume compared to other soldering systems result in even lower running costs. Excellent heat transfer in an inert oxygen free atmosphere without the need of costly nitrogen. Two chamber system with a large touch display makes this machine user friendly, easy to set up and use. Soldering is possible regardless of assembly weight with the same profile.



Transport of boards into the process chamber



Observation window



Vacuum unit inside of process chamber

### Features:

- Comfortable 15" Touch-Screen
- Integrated PC, allows permanent data collection and professional data management
- Permanent data collection
- Unlimited program memory with a large amount of sample programs
- Network capable
- Password protected operation levels
- Energy management system
- Heating power monitoring
- Intelligent Profiling System (IPS) for high-end thermal profile control
- Automatic in- and outlet of the Work Piece Carrier
- Patented vibration and maintenance free transport system
- Two chamber design and medium recovery results in a very low fluid consumption
- Fluid level control and automatic filtering
- Patented vacuum chamber inside of the process chamber
- Controllable vacuum generation set up in steps, multi vacuum or linear mode
- Integrated fans with global bottom cooling
- Minimal maintenance and wear due to all moving parts mounted outside of the process chamber
- Easy access to solder chamber for cleaning and maintenance purposes
- Observation window into the solder chamber
- Exhaust connection
- Cool handling – transport system in cool area

## Options:

### Process extensions

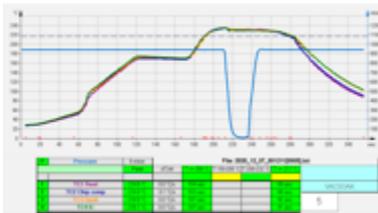
- Infrared pre-heating
- Vapour descent
- Extended pcb cooling
- Patented Rapid Cooling System (RCS)
- Up to 3 additional temperature measurement channels
- Multi-Level Mode for rapid switching between different soldering heights
- Nitrogen floating of the cooling and process chamber

### Software extensions

- Online Temperature Recording Software (TRS) for data analysis and storage including alarm and event log
- Pilot mode, measurement channel for easy temperature-controlled soldering and setting up of profiles
- Various traceability extensions, for automated processes and tracking, ready for Industry 4.0

### Hardware extensions

- Adapter for double sided boards
- Stainless steel grid
- Heavy Duty "HD" model for loads up to 14kg with stronger heating capabilities
- Exhaust system extensions
- 2<sup>nd</sup> Emergency Stop
- Signal light tower
- UPS – Uninterruptable Power Supply
- ReSy – a device for repair of QFPs and BGAs
- Expanded medium filter system including medium levelling and fast cooling system
- Noise protection for vacuum tower
- Chiller for inside or outside use with automatic standby control



Real time profile monitoring



Machine status



Scanner option

## Technical data:

	VAC745	VAC765
Width	1355 mm (53.35")	
Depth	2400 mm (94.49")	2810mm (110.63")
Height	1470 mm (57.87")	
Weight	1030kg	1200kg
Max. PCB size	635 x 444 x70mm (with vacuum) 25.00 x 17.48 x 2.76" 635 x 444 x 80mm (without vacuum) 25.00 x 17.48 x 3.15"	635 x 644 x70mm (with vacuum) 25.00 x 25.35 x 2.76" 635 x 644 x 80mm (without vacuum) 25.00 x 25.35 x 3.15"
Max. load on single carrier	7kg	
Liquid agent filling	40 kg	60 kg
Water connection	1/2" / 2,5 – 5 bar	
Max. heating capacity	10,4kW	13 kW
Average power consumption	5,5 kW/h	5,8 kW/h
Power supply	400 / 230VAC, 50/60Hz	
Main fuse	32A „gl“ or „c“	
External vacuum module	910 x 550 x 650mm (35.83 x 21.65 x 25.59"); 119 kg (262.35 lbs)	

\*\*\*Specifications subject to change without prior notice\*\*\*

D1E126-Datasheet VAC7x5 E-210719